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Application Number	Unknown		
Filing Date	(Herewith)		
First Named Inventor	Efren M. Lacap		
Art Unit	Unknown		
Examiner Name			
Attorney Docket Number	408204		

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Certific	cate under 37 CFR 3.73(b)	is enclosed. (Form PTOISBI	196).	
		SIGNATURE of Applicant or	r Assignee of Rec	ord
Name	David Lidsky, Director of	Design Engineering, Volterr	a Semiconductor (Corporation
Signature	4.887			
Date	8/27/05		Telephone	510-743-1205
	atures of all the inventors			or their representative(s) are required.
	ple forms if more than or of 1 forms are submitted	e signature is required, see	e below*.	
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(and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 3 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the Individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450, DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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PTO/SB/96 (04-03)

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STATEMENT UNDER 37 CFR 3.73(b)					
Applicant/Patent Owner: Efren M. Lacap et al.					
Application No./Patent No.: Unknown	Filed/Issue Date: (Herewith)				
Entitled: WAFER-LEVEL CHIP SCALE PACKAGING					
Volterra Semiconductor Corporation a Corporation					
(Name of Assignee) (Type of	Assignee, e.g., corporation, partnership, university, government agency, etc.)				
states that it is:					
1. the assignee of the entire right, title, and interest; or					
2. an assignee of less than the entire right, title, and interest					
The extent (by percentage) of its ownership interest is%					
in the patent application/patent identified above by virtue of	of either:				
A. An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the Patent and Trademark Office at Reel, Frame, or for which a copy thereof is attached.					
OR					
B. ☐ A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below:					
1. From:					
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3. From:					
The document was recorded in the United States Patent and Trademark Office at					
Reel, Frame, or for which a copy thereof is attached.					
Additional documents in the chain of title are listed on a supplemental sheet.					
Copies of assignments or other documents in the chain of title are attached. [NOTE A separate copy (i.e., the original assignment document or a true copy of the original document) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the USPTO. See MPEP 302.8]					
The undersigned (whose title is supplied below) is empowered to sign this statement on behalf of the assignee.					
8/27/03 Date	While the same of				
	Signature				
(50) 743-1205	Devid Lidsky				
Telephone Number	Typed or printed name				
	Director, Design Engineering Title				
	LING				

This collection of information is required by \$7 CFR 3.73(b). The information is required to obtain or retain a banefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1,14. This collection is estimated to take 12 minutes to complete, including gathering, propering, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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210/431600

Docket No.: 408204

Palent

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/we, the undersigned, Eften M. Lacap, Subhash R. Nariani and Charles Nickel, do hereby sell, assign, and transfer to: Volterra Semiconductor Corporation, a corporation of Delaware, having a place at 3839 Spinnaker Court, Fremont, California 94538 ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent which has been executed by the undersigned concurrently herewith and is entitled:

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and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant, with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

vame:

Efren M. Lacap

Name:

Name:

Date: 8-19-2003

Date: 2/19/03

Data: 8/19/03